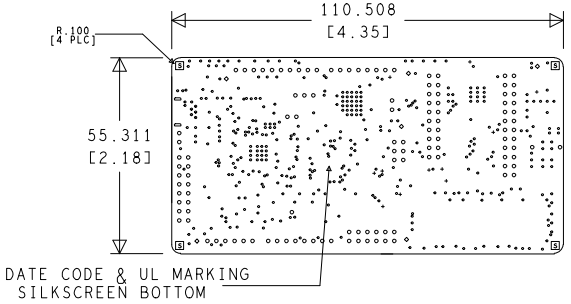
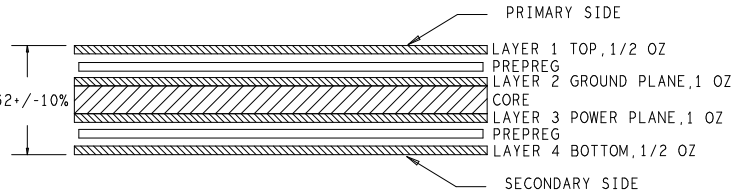
REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
01	ALPHA RELEASE	03/26/14	VRNK
02	BETA RELEASE	03/26/14	VRNK
03	PRODUCTION RELEASE	07/22/14	VRNK
04	PRODUCTION RELEASE	03/01/16	RKPM
05	PRODUCTION RELEASE	03/24/16	RKPM



DRILL CHART: BLE_Pioneer_Rev04				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
•	8.0	+3.0/-3.0	PLATED	427
+	10.0	+3.0/-10.0	PLATED	11
•	28.0	+3.0/-3.0	PLATED	5
○	40.0	+3.0/-3.0	PLATED	122
◇	43.0	+3.0/-3.0	PLATED	6
⊡	125.0	+2.0/-2.0	NON-PLATED	4
▭	74.799x27.598	+3.0/-3.0	PLATED	2

NOTES:(UNLESS OTHERWISE SPECIFIED)

1. RoHS COMPLIANT CERTIFICATION OR MATERIAL DECLARATION REQUIRED
2. MATERIAL:
   A. IS410 OR EQUIVALENT. MATERIAL MUST CONFORM TO UL94V-0.
   B. USE HTE COPPER, AS SPECIFIED IN THE CROSS SECTION DIAGRAM
   C. OVERALL METAL TO METAL THICKNESS AS SPECIFIED IN THE CROSS SECTION
3. DRILLING:
   A. DIAMETERS IN DRILL TABLE ARE FINISHED HOLE SIZES +/-.003 tol. UNLESS OTHERWISE SPECIFIED IN DRILL TABLE.
   B. TEARDROP ALLOWED ON ENTRY OF VIA ON EVERY TRACE LAYER.
4. PLATING:
   COPPER PLATING IN THRU-HOLES .001 min.
5. MARKING:
   A. SILKSCREEN IN WHITE NON-CONDUCTIVE EPOXY INK ON PRIMARY SIDE OF THE BOARD OR BOTH SIDES IF APPLICABLE.
   B. FABRICATOR TO PLACE DATE CODE AND LOGO ON SECONDARY SIDE IN ETCH (PREFERRED) OR SILKSCREEN.
6. FINAL FABRICATION:
   A. SOLDRMASK PRIMARY AND SECONDARY SIDE OF BOARD USING LIQUID PHOTOIMAGABLE MASK MATERIAL OVER BARE COPPER. PER IPC-SM-840. MASK ARTWORKS PROVIDED ARE 1:1. SOLDERMASK COLOR **RED**
7. FINISH:
   A. SHALL BE ELECTROLYTIC NICKEL/GOLD. ELECTROLESS NIKEL / IMMERSION GOLD. (ENIG)
   B. NICKEL THICKNESS: 100-200 MICROINCHES.
   C. GOLD THICKNESS: 3-10 MICROINCHES.
8. BOARDS SHALL BE PURCHASED FROM UL RECOGNIZED VENDORS ONLY AND SHALL BE MARKED IN COPPER ON SECONDARY SIDE OF BOARD WITH VENDORS UL IDENT. FLAMABILITY RATING (94-V0), DATE CODE (WWYY), AND RoHS COMPILANT SYMBOL.
9. MANUFACTURE BOARD TO BE IN ACCORDANCE WITH PERFORMANCE STANDARD IPC-6011/6012 CLASS 2 BOARD TO BE INSPECTED PER IPC-600-A CLASS 2.
10. MAXIMUM WRAP OR TWIST SHALL NOT EXCEED .007 in/in.
11. TESTING:
   A. FABRICATOR TO ADD TEST STRUCTURES OR CUPONS AS NEEDED.
   B. T-LINE IMPEDENCE TO BE TESTED OR GUARANTEE WITHIN 10% IF SPECIFIED IN THE CROSS SECTION. TOLERANCE TO BE +/-10% UNLESS OTHERWISE SPECIFIED.



NOTE: 9 MIL 16 MIL SPACING TRACES ON LAYER 1 DIFFERENTIAL IMPEDANCE CONTROLLED TO 90 OHMS +/- 10% TESTED

UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN INCHES
TOLERANCES ON; ANGLES +/- 2°
2 PL DECIMALS +/- .010
3 PL DECIMALS +/- .005
THIRD ANGLE PROJECTIONS

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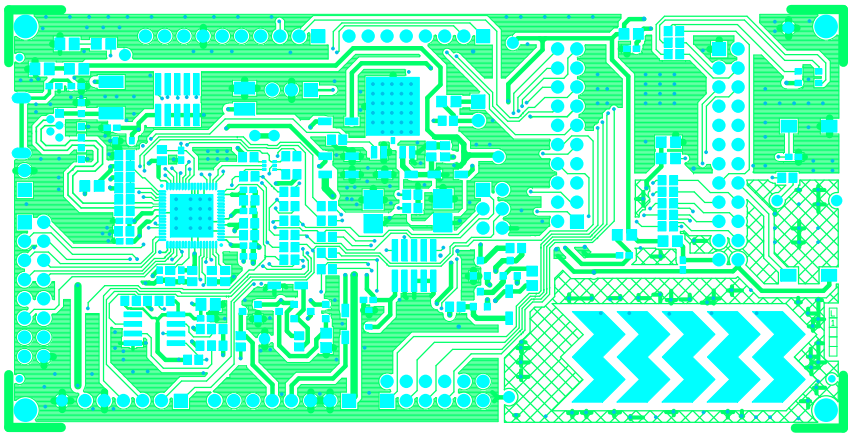
SIGNATURES		DATE
DRAWN	PRAO	03/24/16
CHECKED	RKPM	03/24/16
ENGRG	RKPM	03/24/16
ISSUED		

CYPRESS SEMICONDUCTOR
198 CHAMPION COURT
SAN JOSE, CA 95134
(408) 943-2600

FABRICATION DRAWING
CY8CKIT-042-BLE-A PIONEER BASEBOARD

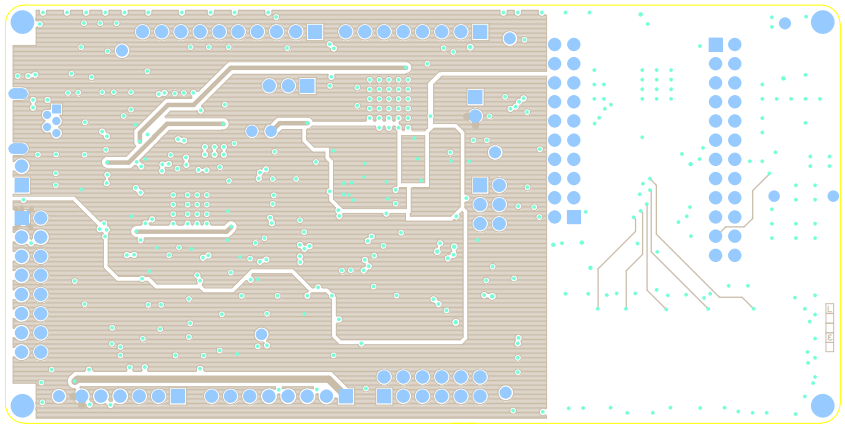
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SCALE: 1/1 SHEET: 1 OF 1

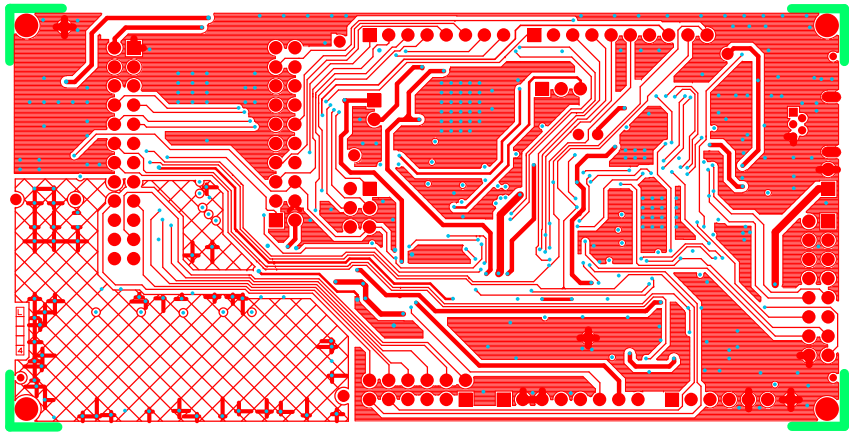


600-60352-01 REV05 PRIMARY SIDE

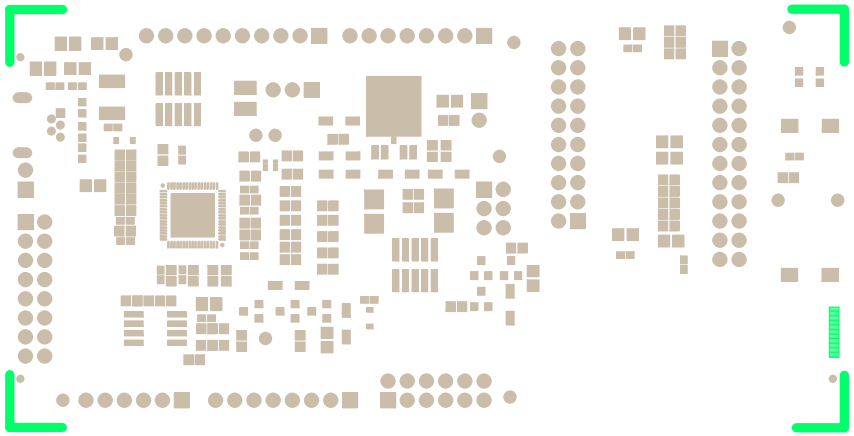
600-60352-01 REV05 GND LAYER



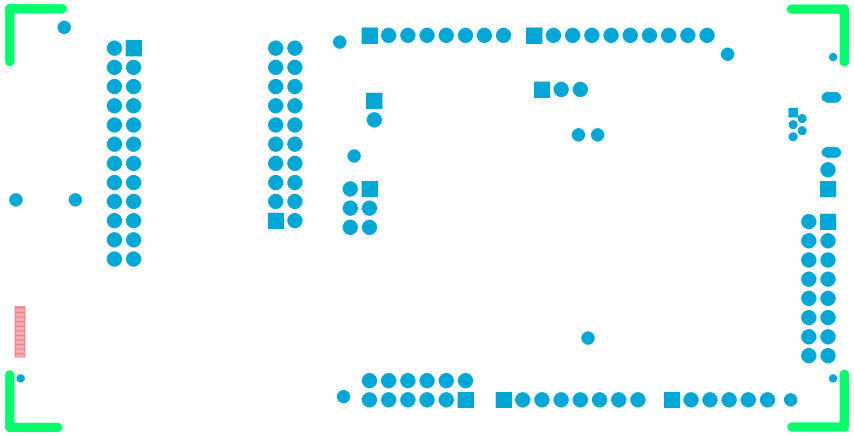
600-60352-01 REV05 POWER LAYER



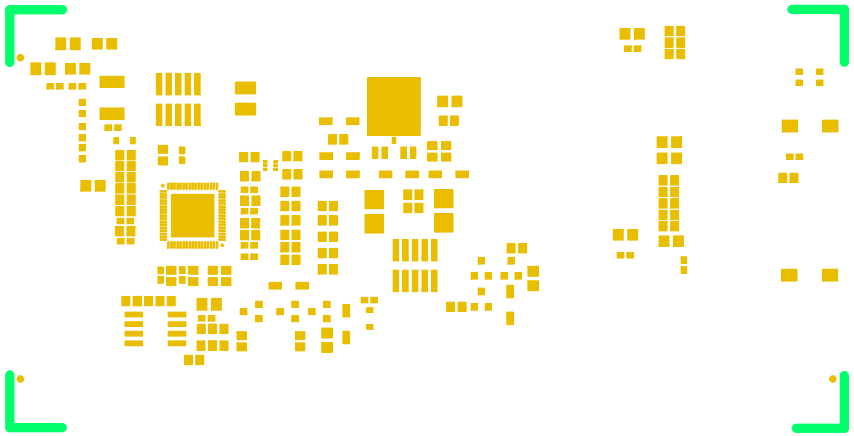
600-60352-01 REV05 SECONDARY SIDE



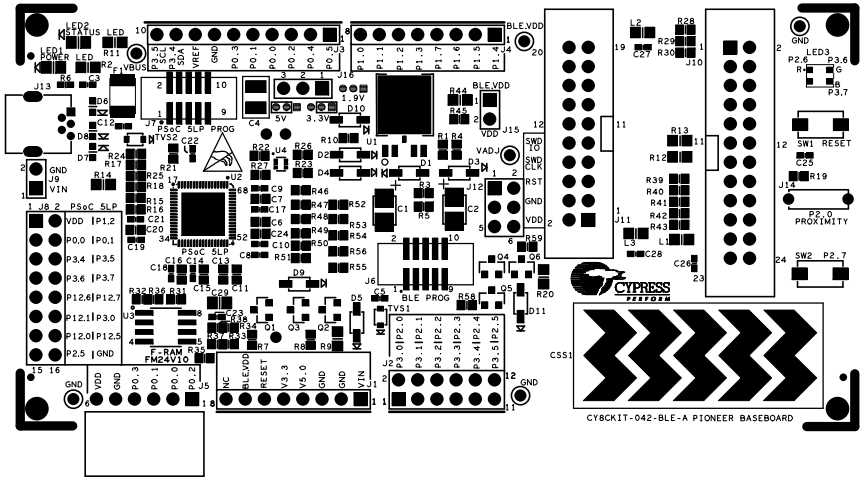
600-60352-01 REV05 PRIMARY SOLDERMASK



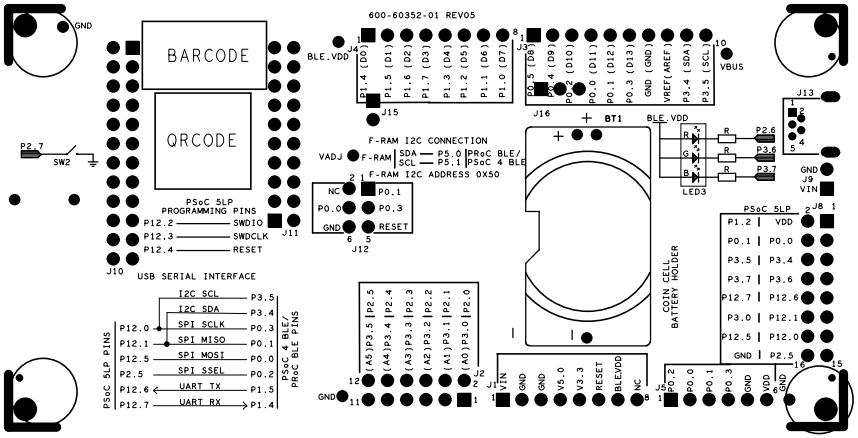
600-60352-01 REV05 SECONDARY SIDE



600-60352-01 REV05 PRIMARY SOLDERPASTE



600-60352-01 REV05 PRIMARY SILKSCREEN



600-60352-01 REV05 SECONDARY SILKSCREEN